IN THE CLAIMS

Please amend claims 1, 6 and 32:

1. (currently amended) A method of manufacturing a conductive lamp housing, comprising depositing particles by direct metallization to form a layer of conductive material on a ~~contoured~~generally non-planar surface of a substrate that forms part of the lamp housing, in order to form part of one or more electrical spray circuits when said conductive material is connected to at least one or more power sources and one or more light sources.

2. (previously presented) The method of manufacturing a lamp housing of claim 1, wherein the direct metallization deposition of the layer of conductive material is deposited by vacuum deposition in a vacuum chamber.

3. (original) The method of manufacturing a lamp housing of claim 2, wherein the layer of conductive material is deposited by sputter vacuum deposition.

4. (original) The method of manufacturing a lamp housing of claim 2, wherein the layer of conductive material is deposited by cathodic arc vacuum deposition.

5. (original) The method of manufacturing a lamp housing of claim 2, wherein the layer of conductive material is deposited by E-beam vacuum deposition.

6. (currently amended) The method of manufacturing a lamp housing of claims 1 ~~or 11~~, wherein the layer of conductive material is metal.

7. (canceled)

8. (original) The method of manufacturing a lamp housing of claim 1, further comprising a step of forming distinct electrical pathways in the layer of conductive material during deposition.

9. (original) The method of manufacturing a lamp housing of claim 8, wherein the distinct electrical pathways are formed by masking the lamp housing prior to deposition of the layer of conductive material on the lamp housing.

10. (original) The method of manufacturing a lamp housing of claim 1, further comprising a step of depositing a reflective coating on the substrate.

11. (canceled)

12. (original) The method of manufacturing a lamp housing of claim 1, further comprising a step of applying a spray seal on said substrate.

13. (original) The method of manufacturing a lamp housing of claim 1, further comprising a step of applying a protective coating to said conductive material.

14. (original) The method of manufacturing a lamp housing of claim 1, wherein the step of depositing a conductive layer further comprises depositing one or more terminals for contacting said light sources.

15. (original) The method of manufacturing a lamp housing of claim 1, wherein the step of depositing a conductive further layer comprises depositing at least one connection for electrically connecting said conductive layer to said power sources.

16. (previously presented) A lamp housing comprising a substrate, further comprising a conductive layer for one or more electrical circuits deposited directly on said substrate, wherein said conductive layer is 1 to 4 microns thick.

17. (original) The lamp housing of claim 16, wherein the conductive layer is formed by vacuum deposition of the electrical circuits on said substrate.

18. (original) The lamp housing of claim 17, wherein the conductive layer is directly embedded in said substrate.

19. (original) The lamp housing of claim 16, further comprising one or more openings in said lamp housing for one or more light sources.

20. (original) The lamp housing of claim 17, further comprising one or more terminals attached to the conductive layer at said openings.

21. (original) The lamp housing of claim 17, wherein said light sources comprise one or more light emitting diodes.

22. (original) The lamp housing of claim 17, wherein said light sources comprise one or more incandescent lamps.

23. (original) The lamp housing of claim 16, further comprising a reflective coating.

24. (canceled)

25. (original) The lamp housing of claim 16, further comprising a spray seal.

26. (original) The lamp housing of claim 16, further comprising a protective coating on said conductive layer.

27. (canceled)

28. (original) The lamp housing of claim 16, further comprising a single connection for electrically connecting said circuits to one or more power sources.

29. (original) The lamp housing of claim 16, wherein said housing comprises one or more molded channels to facilitate receipt of said conductive layer.

30. (original) The lamp housing of claim 16, wherein said housing comprises one or more smooth corners to facilitate receipt of said conductive layer.

31. (previously presented) The lamp housing of claim 1 wherein the lamp housing is comprised of a thermoplastic material.

32. (currently amended) The lamp housing of claim 1 wherein the ~~contoured~~generally non-planar surface is comprised of a plurality of compartments, each compartment being generally concave.

33. (previously presented) The method of manufacturing a lamp housing of claim 10, wherein the conductive material and reflective coating are formed on the substrate within the same vacuum chamber.

34. (previously presented) The method of manufacturing a lamp housing of claim 10 wherein the conductive material and reflective coating are formed on the substrate simultaneously in the same vacuum chamber.

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